

FMBM5551

NPN General-Purpose Amplifier

Features

- · This device has matched dies
- Sourced from process 16
- See MMBT5551 for characteristics

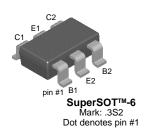


Figure 1. Device Package

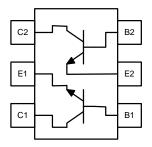


Figure 2. Internal Connection

Ordering Information

Part Number	Top Mark	Package	Packing Method
FMBM5551	3S2	SSOT 6L	Tape and Reel

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}\text{C}$ unless otherwise noted.

Symbol	Parameter	Value	Unit
V _{CEO}	Collector-Emitter Voltage	160	V
V _{CBO}	Collector-Base Voltage	180	V
V _{EBO}	Emitter-Base Voltage	6	V
I _C	Collector Current (DC)	600	mA
T _J	Junction Temperature	150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C

Thermal Characteristics (1), (2)

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Value	Unit
P _D	Power Dissipation (T _C = 25°C)	0.7	W
	Derate Above 25°C	5.6	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	180	°C/W

Notes:

- 1. P_D total, for both transistors. For each transistor, P_D = 350 mW.
- 2. PCB size: FR-4, 76 mm x 114 mm x 1.57 mm (3.0 inch x 4.5 inch x 0.062 inch) with minimum land pattern size.

Electrical Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Max.	Unit
BV _{CEO}	Collector-Emitter Breakdown Voltage	$I_C = 1 \text{ mA}, I_B = 0$	160		V
BV _{CBO}	Collector-Base Breakdown Voltage	$I_C = 100 \mu A, I_E = 0$	180		V
BV _{EBO}	Emitter-Base Breakdown Voltage	$I_E = 10 \mu A, I_C = 0$	6		V
1	Collector Cut-Off Current	V _{CB} = 120 V, I _E = 0		50	nA
I _{CBO}	Collector Cut-Oil Current	V _{CB} = 120 V, I _E = 0, T _A = 100°C		50	μΑ
I _{EBO}	Emitter Cut-Off Current	$V_{EB} = 4 \text{ V}, I_{C} = 0$		50	nA
h _{FE1}	DC Current Gain	V _{CE} = 5 V, I _C = 1 mA	80		
DIVID1	Variation Ratio of h _{FE1} Between Die 1 and Die 2	h _{FE1} (Die1) / h _{FE1} (Die2)	0.9	1.1	
h _{FE2}	DC Current Gain	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$	80	250	
DIVID2	Variation Ratio of h _{FE2} Between Die 1 and Die 2	h _{FE2} (Die1) / h _{FE2} (Die2)	0.95	1.05	
h _{FE3}	DC Current Gain	$V_{CE} = 5 \text{ V}, I_{C} = 50 \text{ mA}$	30		
DIVID3	Variation Ratio of h _{FE3} Between Die 1 and Die 2	h _{FE3} (Die1) / h _{FE3} (Die2)	0.9	1.1	
\/ (aat)	O-H- stan Forthan O-ton-ti-m Mallana	I _C = 10 mA, I _B = 1 mA		0.15	- V
V _{CE} (sat)	Collector-Emitter Saturation Voltage	$I_C = 50 \text{ mA}, I_B = 5 \text{ mA}$		0.20	
V _{BE} (sat)	Base-Emitter Saturation Voltage	$I_C = 10 \text{ mA}, I_B = 1 \text{ mA}$		1	V
v _{BE} (sat)	Base-Emitter Saturation Voltage	$I_C = 50 \text{ mA}, I_B = 5 \text{ mA}$		1	v
V _{BE} (on)	Base-Emitter On Voltage	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$		1	V
DEL	Difference of V _{BE} (on) Between Die1 and Die 2	V _{BE} (on)(Die1) - V _{BE} (on)(Die2)	-8	8	mV
C _{ob}	Output Capacitance	V _{CB} = 10 V, I _E = 0, f = 1 MHz		6	pF
C _{ib}	Input Capacitance	V _{EB} = 0.5 V, I _C = 0, f = 1 MHz		20	pF
f _T	Current Gain Bandwidth Product	V _{CE} = 10 V, I _C = 10 mA, f = 100 MHz	100	300	MHz
NF	Noise Figure	V_{CE} = 5 V, I_{C} = 200 μA, f = 1 MHz, R_{S} = 20 kΩ, B = 200 Hz		8	dB
h _{fe}	Small Signal Current Gain	$V_{CE} = 10 \text{ V}, I_{C} = 1.0 \text{ mA},$ f = 10 kHz	50	250	

Typical Performance Characteristics

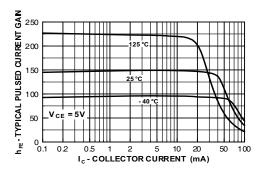


Figure 3. Typical Pulsed Current Gain vs. Collector Current

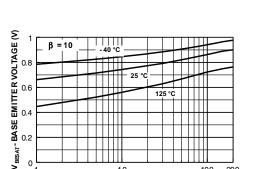


Figure 5. Base-Emitter Saturation Voltage vs. Collector Current

I - COLLECTOR CURRENT (mA)

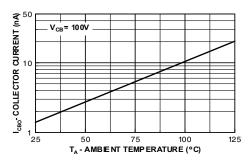


Figure 7. Collector Cut-Off Current vs. Ambient Temperature

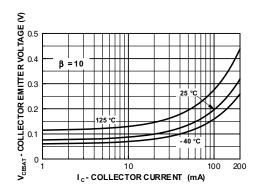


Figure 4. Collector-Emitter Saturation Voltage vs. Collector Current

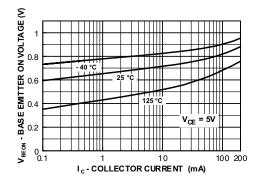


Figure 6. Base-Emitter On Voltage vs. Collector Current

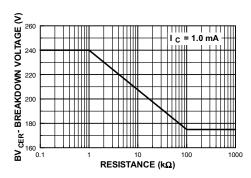


Figure 8. Collector-Emitter Breakdown Voltage with Resistance Between Emitter-Base

Typical Performance Characteristics (Continued)

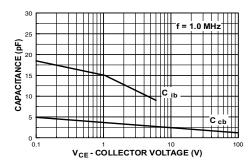


Figure 9. Input and Output Capacitance vs. Reverse Voltage

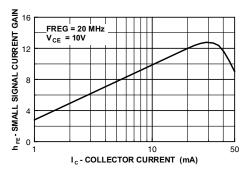


Figure 10. Small Signal Current Gain vs. Collector Current

Physical Dimensions SYMM 0.95 -0.95 A 1.00 В 3.00 2.60 2.60 3 -0.50 0.30 0.95 0.70 MIN ⊕ 0.20M C A B 1.90 LAND PATTERN RECOMMENDATION (0.30) -SEE DETAIL A -1.10 MAX 1.00 0.70 Ċ 0.10 △ 0.10 C NOTES: UNLESS OTHERWISE SPECIFIED GAGE PLANE THIS PACKAGE CONFORMS TO JEDEC MO-193. VAR. AA, ISSUE C, DATED JANUARY 2000. ALL DIMENSIONS ARE IN MILLIMETERS. 0.25 0.55 0.35 SEATING PLANE -0.60 REF DETAIL A

Figure 11. 6-LEAD, SUPERSOT6, JEDEC MO-193, 1.6 MM WIDE

MA06AREVD

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and h

Phone: 81-3-5817-1050

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

♦ © Semiconductor Components Industries, LLC

www.onsemi.com